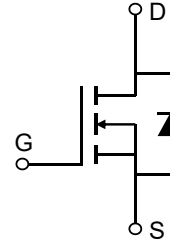


Description

Features

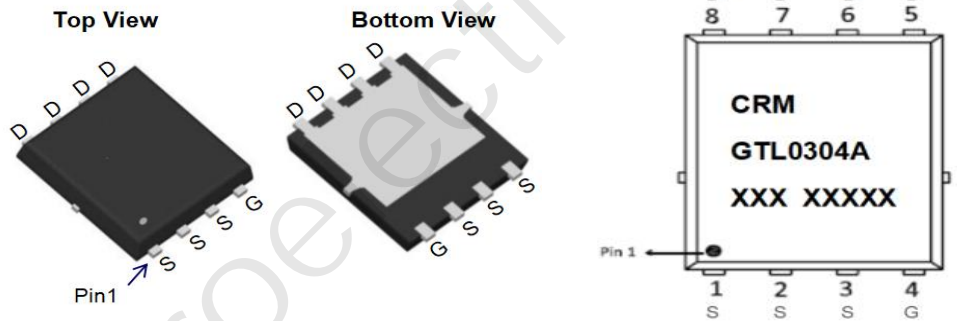
- 30V, 100A
- $R_{DS(ON)}$ Typ = 2.6mΩ @ $V_{GS} = 10V$
- $R_{DS(ON)}$ Typ = 3.8mΩ @ $V_{GS} = 4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_d s TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

| Device | Marking | Package | Outline | Reel Size | Reel (pcs) | Per Carton (pcs) |
|-------------|-------------|------------|---------|-----------|------------|------------------|
| CRMGTL0304A | CRMGTL0304A | PDFN5x6-8L | TAPING | 13" | 5000 | 50000 |

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Value | Units | |
|-----------------------------------|---|------------------------|-------|---|
| V _{DS} | Drain-to-Source Voltage | 30 | V | |
| V _{GS} | Gate-to-Source Voltage | ±20 | V | |
| I _D | Continuous Drain Current | T _C = 25°C | 100 | A |
| | | T _C = 100°C | 60 | A |
| I _{DM} | Pulsed Drain Current ⁽¹⁾ | 400 | A | |
| E _{AS} | Single Pulsed Avalanche Energy ⁽²⁾ | 156 | mJ | |
| P _D | Power Dissipation | T _C = 25°C | 56.8 | W |
| R _{θJC} | Thermal Resistance, Junction to Case | 2.2 | °C/W | |
| T _J , T _{STG} | Junction & Storage Temperature Range | -55 to 150 | °C | |

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--|--|---|------|------|------|------|
| Off Characteristics | | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | I _D = 250μA, V _{GS} = 0V | 30 | - | - | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 30V, V _{GS} = 0V | - | - | 1.0 | μA |
| I _{GSS} | Gate-Body Leakage Current | V _{DS} = 0V, V _{GS} = ±20V | - | - | ±100 | nA |
| On Characteristics | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} , I _D = 250μA | 1.1 | 1.6 | 2.1 | V |
| R _{DS(ON)} | Static Drain-Source ON-Resistance ⁽³⁾ | V _{GS} = 10V, I _D = 20A | - | 2.6 | 3.4 | mΩ |
| | | V _{GS} = 4.5V, I _D = 10A | - | 3.8 | 5.0 | mΩ |
| Dynamic Characteristics | | | | | | |
| C _{iss} | Input Capacitance | V _{GS} = 0V, V _{DS} = 15V, f = 1MHz | - | 3154 | - | pF |
| C _{oss} | Output Capacitance | | - | 372 | - | pF |
| C _{rss} | Reverse Transfer Capacitance | | - | 306 | - | pF |
| Q _g | Total Gate Charge | V _{GS} = 0 to 10V V _{DS} = 15V, I _D = 30A | - | 58 | - | nC |
| Q _{gs} | Gate Source Charge | | - | 12 | - | nC |
| Q _{gd} | Gate Drain("Miller") Charge | | - | 13 | - | nC |
| Switching Characteristics | | | | | | |
| t _{d(on)} | Turn-On DelayTime | V _{GS} = 10V, V _{DD} = 15V I _D = 30A, R _{GEN} = 3Ω | - | 11 | - | ns |
| t _r | Turn-On Rise Time | | - | 29 | - | ns |
| t _{d(off)} | Turn-Off DelayTime | | - | 47 | - | ns |
| t _f | Turn-Off Fall Time | | - | 18 | - | ns |
| Drain-Source Diode Characteristics and Max Ratings | | | | | | |
| I _S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | 100 | A |
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | 400 | A |
| V _{SD} | Drain to Source Diode Forward Voltage | V _{GS} = 0V, I _S = 30A | - | - | 1.2 | V |
| t _{rr} | Body Diode Reverse Recovery Time | I _F = 30A, di/dt = 100A/us | - | 16 | - | ns |
| Q _{rr} | Body Diode Reverse Recovery Charge | | - | 7 | - | nC |

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 15\text{V}$, $V_G = 10\text{V}$, $R_G = 25\text{ohm}$, $L = 0.5\text{mH}$, $I_{AS} = 25\text{A}$
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Typical Performance Characteristics

Figure 1: Output Characteristics

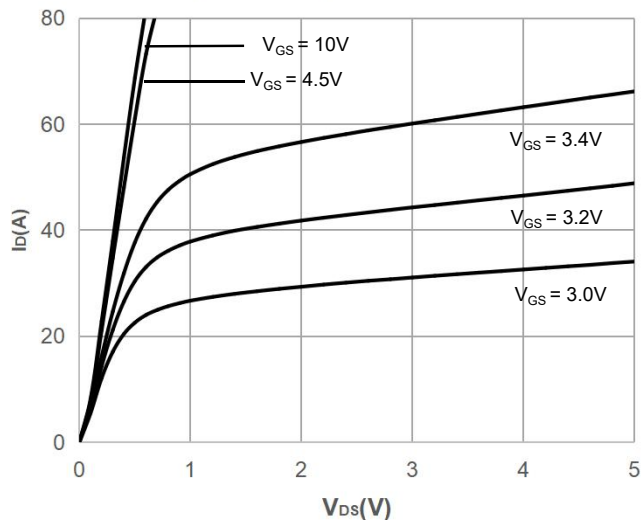


Figure 2: Typical Transfer Characteristics

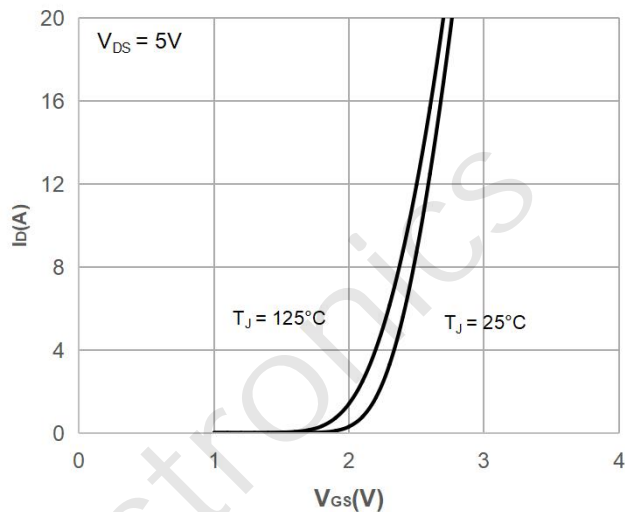


Figure 3: On-resistance vs. Drain Current

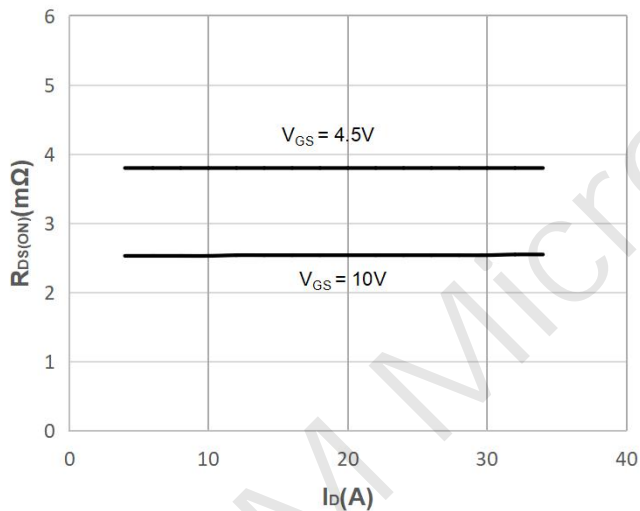


Figure 4: Body Diode Characteristics

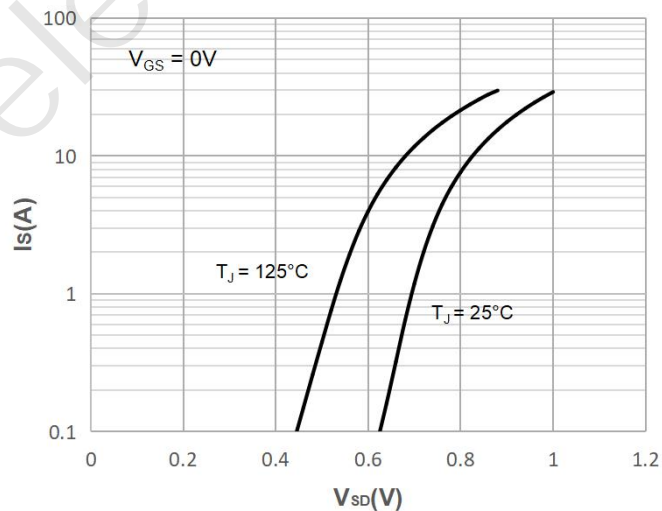


Figure 5: Gate Charge Characteristics

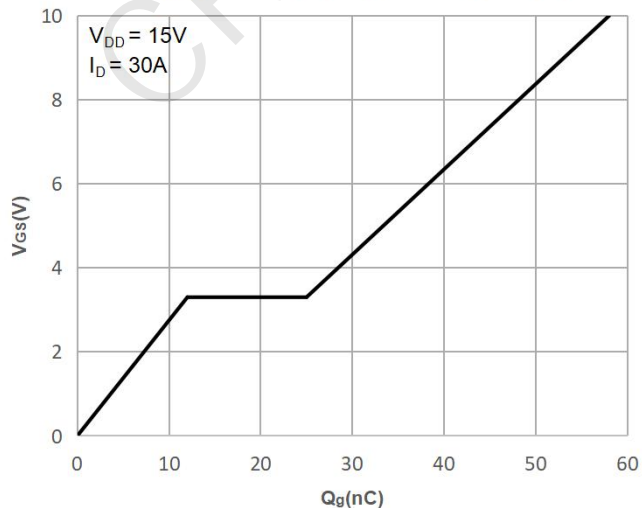
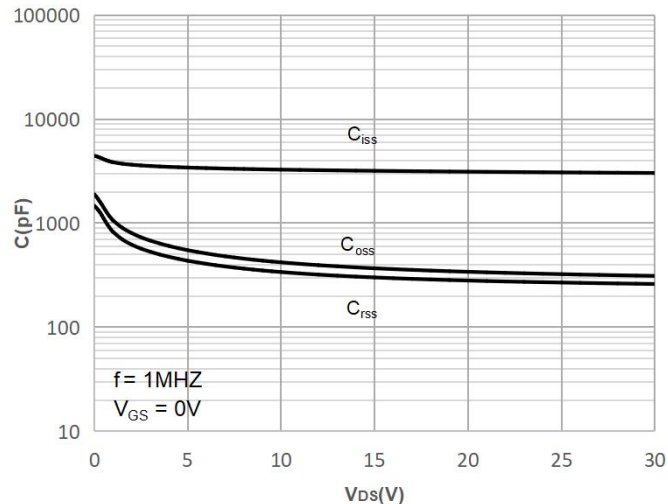


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

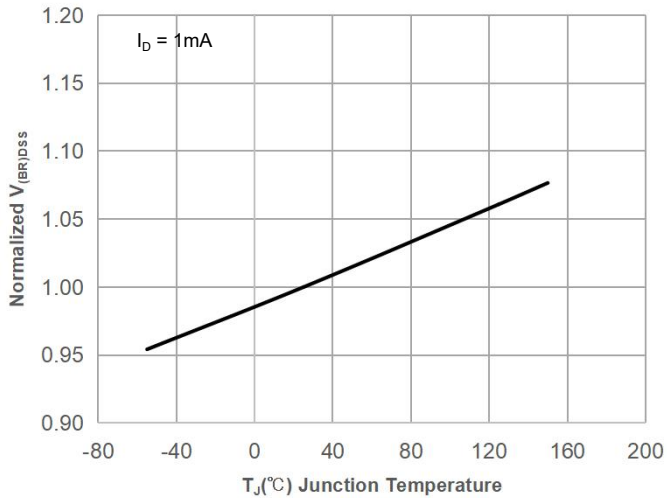


Figure 8: Normalized on Resistance vs. Junction Temperature

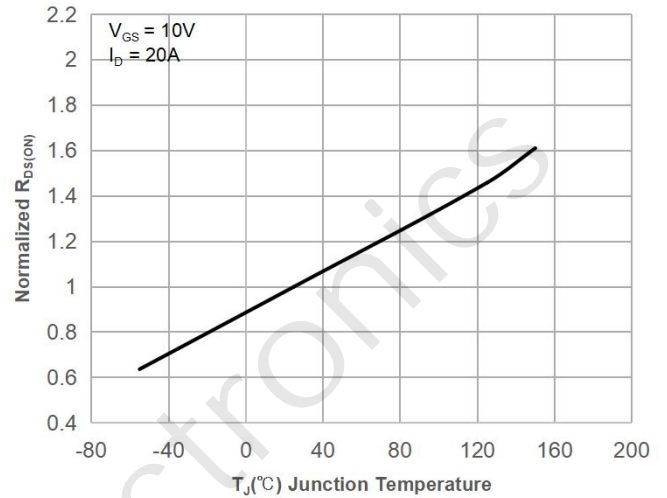


Figure 9: Maximum Safe Operating Area

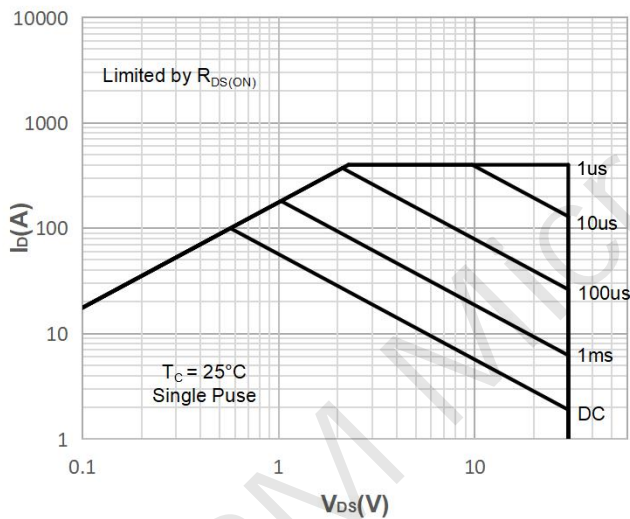


Figure 10: Maximum Continuous Driand Current vs. Case Temperature

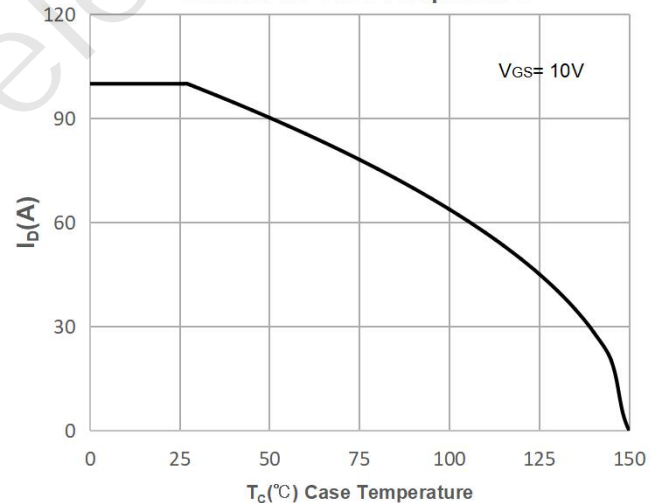


Figure 11: Normalized Maximum Transient Thermal Impedance

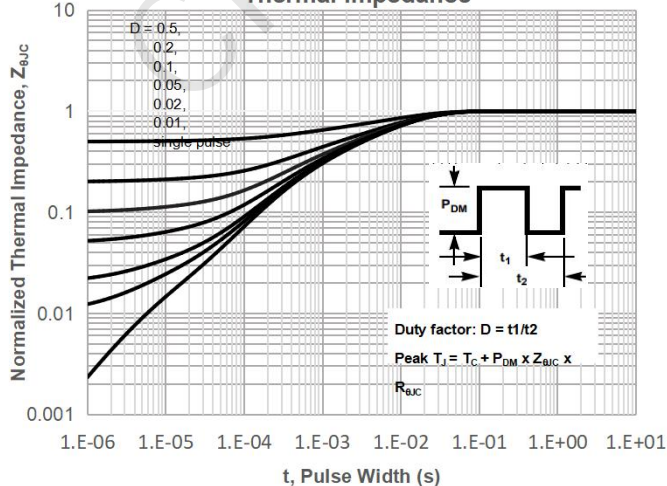
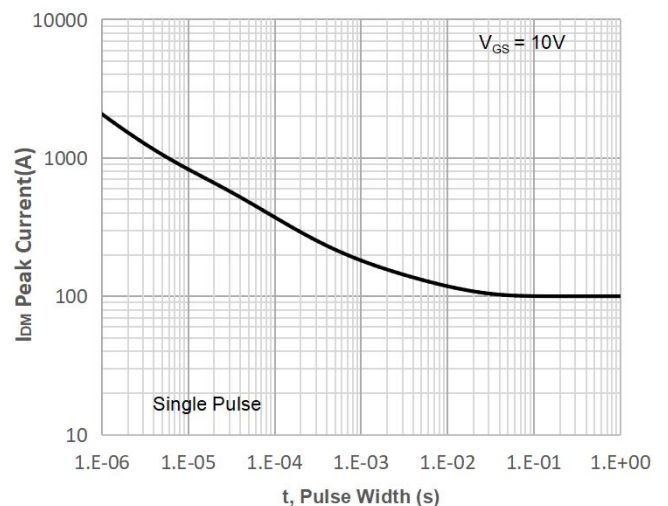


Figure 12: Peak Current Capacity



Test Circuit

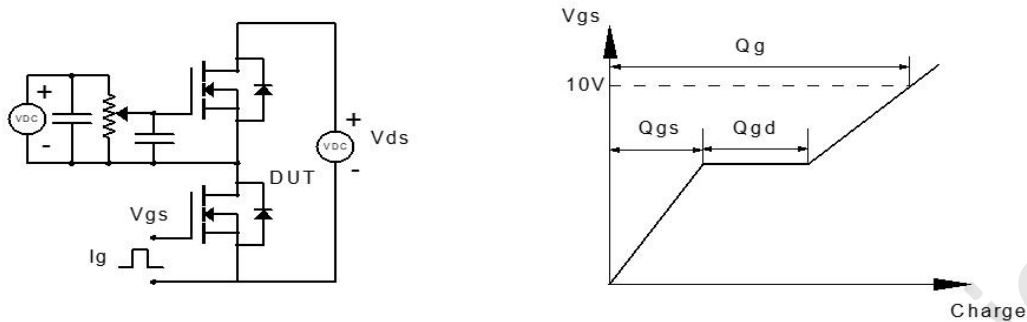


Figure 1: Gate Charge Test Circuit & Waveform

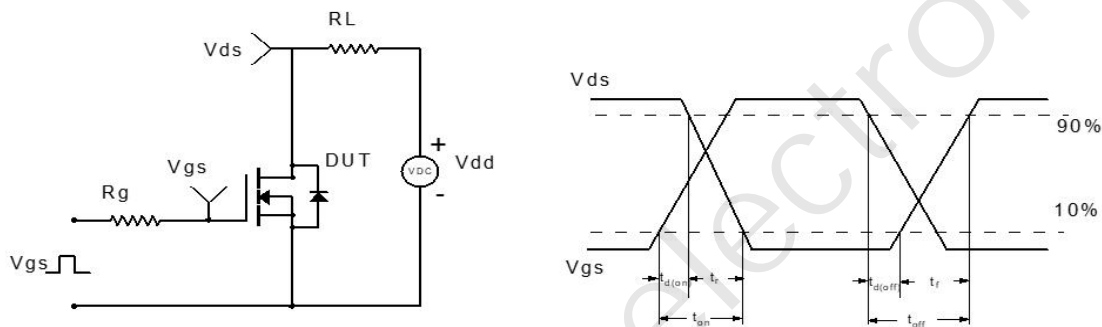


Figure 2: Resistive Switching Test Circuit & Waveform

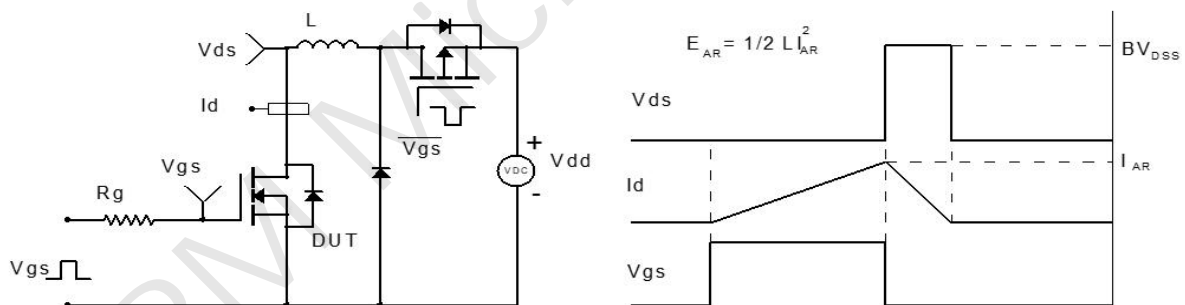


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

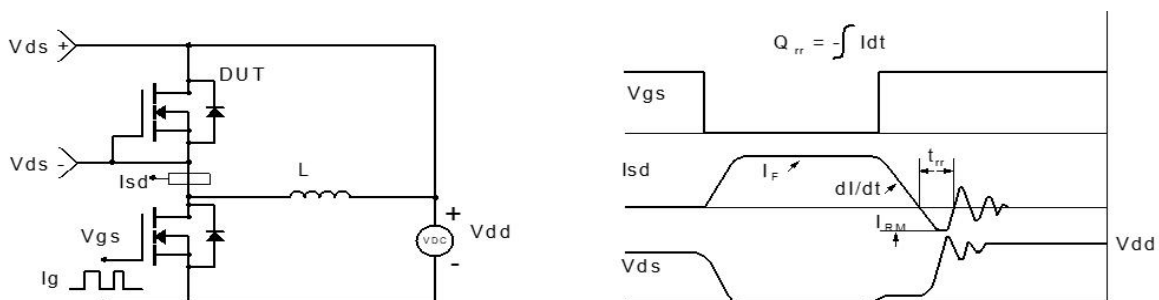
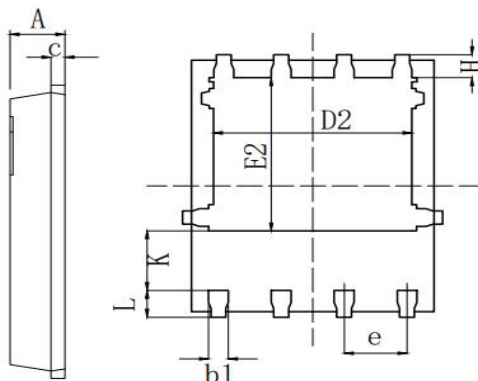
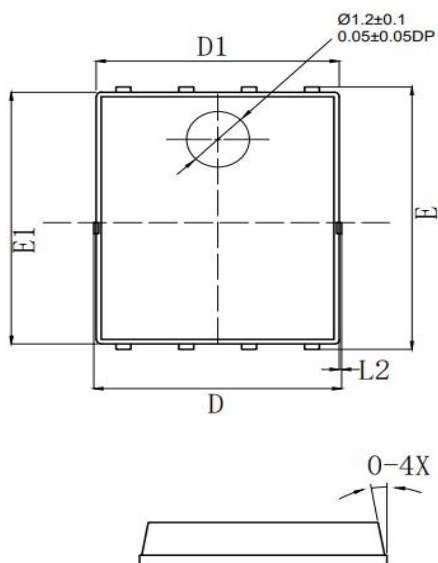


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(PDFN5x6-8L)




| SYMBOL | MILLIMETER | | |
|--------|------------|------|------|
| | MIN | NOM | MAX |
| A | 0.90 | 1.00 | 1.10 |
| b | 0.25 | 0.30 | 0.35 |
| b1 | 0.30 | 0.40 | 0.45 |
| c | 0.22 | 0.25 | 0.28 |
| D | — | — | 5.30 |
| D1 | 4.90 | 5.05 | 5.20 |
| D2 | 3.90REF | | |
| E | 6.00 | 6.15 | 6.30 |
| E1 | 5.70 | 5.85 | 6.00 |
| E2 | 3.50REF | | |
| e | 1.10 | 1.27 | 1.40 |
| H | 0.51 | 0.61 | 0.71 |
| K | 1.10 | — | — |
| L | 0.51 | 0.61 | 0.71 |
| L2 | — | — | 0.10 |
| Φ | 8° | — | 12° |

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